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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/758,188	01/15/2004	In Su Kim	20063/OG03-046	5382
34431 7	590 12/21/2005		EXAM	INER
HANLEY, FLIGHT & ZIMMERMAN, LLC			SMITH, BRADLEY	
20 N. WACKE SUITE 4220	ER DRIVE		ART UNIT	PAPER NUMBER
CHICAGO, II	CHICAGO, IL 60606		2891	

DATE MAILED: 12/21/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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•	Application No.	Applicant(s)	N
	10/758,188	KIM, IN SU	
Office Action Summary	Examiner	Art Unit	
	Bradley K. Smith	2891	
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the o	correspondence addre	9ss
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	OATE OF THIS COMMUNICATION 136(a). In no event, however, may a reply be tirwill apply and will expire SIX (6) MONTHS from e. cause the application to become ABANDONE	N. nely filed the mailing date of this commodity D (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on 10/5/	s action is non-final. Ince except for formal matters, pro		erits is
Disposition of Claims		. •	
4) ☐ Claim(s) 1 and 3-12 is/are pending in the apple 4a) Of the above claim(s) is/are withdra 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1 and 3-6 is/are rejected. 7) ☐ Claim(s) 7-12 is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	own from consideration.		
Application Papers		. •	
9)☐ The specification is objected to by the Examine 10)☒ The drawing(s) filed on 05 October 2005 is/are Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11)☐ The oath or declaration is objected to by the Examine	e: a)⊠ accepted or b)⊡ objected drawing(s) be held in abeyance. Se ction is required if the drawing(s) is ob	e 37 CFR 1.85(a). ejected to. See 37 CFR	• •
Priority under 35 U.S.C. § 119		- •	
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	ts have been received. ts have been received in Applicat prity documents have been receive tu (PCT Rule 17.2(a)).	ion No ed in this National Sta	age
Attachment(s) 1) ☑ Notice of References Cited (PTO-892)	4) 🔲 Interview Summary	(PTO-413)	
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	Paper No(s)/Mail D	ate Patent Application (PTO-15	52)

DETAILED ACTION

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 1. Claims 1, 3-5 are rejected under 35 U.S.C. 103(a) as being unpatentable over Dong et al. (KR2003094442) in view of Okumura et al. Dong et al. disclose depositing an oxide layer, a first conducting layer for a floating gate, a dielectric layer, and a second conducting layer for a control gate in sequence on a semiconductor substrate including a device isolation layer; forming gates by removing some part of the oxide layer, the first conducting layer, the dielectric layer, and the second conducting layer; forming a mask pattern for a self-aligned source over the substrate including the gates'. removing the device isolation layer exposed between the gates; performing an ion implantation process', and eliminating damage generated during the ion implantation process or the removal process of the device isolation layer (see detailed description). With regards to claim 3 Dong et al. disclose the first and second conductive layers are formed of polysilicon. With regards to claim 4, Dong et al. disclose and ONO structure (212, 213, 214). With respect to claim 5, Dong et al. inherently disclose the use of dry etching. However Dong et al. fails to disclose washing the substrate and forming an insulation layer, whereas Okumura et al. disclose washing the substrate and forming an insulation layer. Therefore it would have been obvious to one of ordinary skill in the art

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at the time the invention was made to combine the teachings of Dong et al. and

Okumura et al. because washing the substrate would remove any defects that would interfere in the formation of the insulation layer.

2. Claim1, 3-5 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yang et al. (US Patent 6,784,061) in view of Okumura et al. Yang disclose depositing an oxide layer, a first conducting layer for a floating gate, a dielectric layer, and a second conducting layer for a control gate in sequence on a semiconductor substrate including a device isolation layer; forming gates by removing some part of the oxide layer, the first conducting layer, the dielectric layer, and the second conducting layer; forming a mask pattern for a self-aligned source over the substrate including the gates', removing the device isolation layer exposed between the gates; performing an ion implantation process', and eliminating damage generated during the ion implantation process or the removal process of the device isolation layer (eliminating the damage would be inherent since the ion implant has to be annealed in order to activate the ions) (see figure 6 and column 3 lines 5-25). With regards to claim 3 Yang et al. disclose the first and second conductive layers are formed of polysilicon (column 1 lines 60-65). With regards to claim 4, Yang et al. disclose and ONO structure (column 1 lines 60-65). With respect to claim 5, Yang et al. disclose the use of dry etching (column 3 lines 5-25). However Yang et al. fails to disclose washing the substrate and forming an insulation layer, whereas Okumura et al. disclose washing the substrate and forming an insulation layer. Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to combine the teachings of Yang et al. and Okumura et al.

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because washing the substrate would remove any defects that would interfere in the formation of the insulation layer.

Claim 6 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yang et al. (US Patent 6,784,061) in view of Okumura et al. Yang et al. and Okumura disclose the claimed invention except for applying a top power between 800W and 1500W under a pressure between 100 mTorr and 300 mTorr. It would have been obvious to one of ordinary skill in the art at the time the invention was made to applying a top power between 800W and 1500W under a pressure between 100 mTorr and 300 mTorr, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233. Furthermore the particular power and pressure are well within normal parameters.

Allowable Subject Matter

- 3. Claims 7-12 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
- 4. The following is a statement of reasons for the indication of allowable subject matter: the prior art of record neither teaches nor suggests within the context of the entire claim, dry etch using C4F8, CHF3, O2 and Ar at particular pressures (claim 7), the damage is removed by a chemical dry etch process (claims 8-12).

Allowable Subject Matter

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The indicated allowability of claim 2 is withdrawn in view of the newly discovered reference(s) to Okumura.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Bradley K. Smith whose telephone number is 571-272-1884. The examiner can normally be reached on 10-6.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on 571-272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

> Bradley K Smith Primary Examiner

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